



#### **UPDATED 04/24/2008**

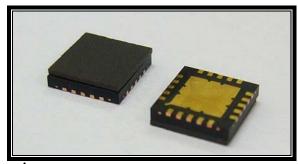
## 17.0 - 20.0 GHz Surface-Mounted PA

### **FEATURES**

- 17.0 20.0 GHz Operating Frequency Range
- 29.0dBm Output Power at 1dB Compression
- 13.0 dB Typical Small Signal Gain
- -40dBc OIMD3 @Each Tone Pout 18.5dBm

### **APPLICATIONS**

- Point-to-point and point-to-multipoint radio
- Military Radar Systems





Caution! ESD sensitive device.

# ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C, 50 ohm, VDD=7V, IDQ=760mA)

SYMBOL	PARAMETER/TEST CONDITIONS	MIN	TYP	MAX	UNITS
F	Operating Frequency Range	17.0		20.0	GHz
P1dB	Output Power at 1dB Gain Compression	28.0	29.0		dBm
Gss	Small Signal Gain	11.0	13.0		dB
OIMD3	Output 3 <sup>rd</sup> Order Intermodulation Distortion @∆f=10MHz, Each Tone Pout 18.5dBm		-40	-37	dBc
Input RL	Input Return Loss		-10		dB
Output RL	Output Return Loss		-10		dB
ldss	Saturate Drain Current V <sub>DS</sub> =3V, V <sub>GS</sub> =0V	860	1070	1290	mA
$V_{DD}$	Power Supply Voltage		7	8	V
Rth	Thermal Resistance <sup>1</sup>		10		°C/W
Tb	Operating Base Plate Temperature	-35		+85	°C

## ABSOLUTE MAXIMUM RATINGS FOR CONTINUOUS OPERATION<sup>2,3</sup>

SYMBOL	SYMBOL CHARACTERISTIC CONTINU	
$V_{DS}$	Drain to Source Voltage	8 V
$V_{GS}$	Gate to Source Voltage	-4 V
I <sub>DD</sub>	Drain Current	Idss
I <sub>GSF</sub>	Forward Gate Current	15mA
P <sub>IN</sub>	Input Power	@ 3dB compression
T <sub>CH</sub>	Channel Temperature	150°C
T <sub>STG</sub>	Storage Temperature	-65/150°C
$P_{T}$	Total Power Dissipation	12.6W

<sup>1.</sup> Measured result when used with Excelics recommended evaluation board.

<sup>2.</sup> Operating the device beyond any of the above rating may result in permanent damage.

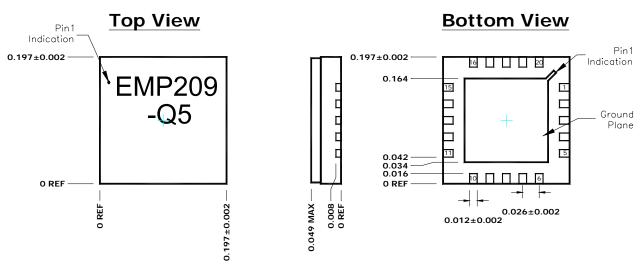
<sup>3.</sup> Bias conditions must also satisfy the following equation  $V_{DS}^*I_{DS} < (T_{CH} - T_{HS})/R_{TH}$ ; where  $T_{HS}$  = ambient temperature



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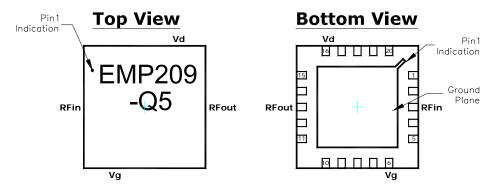
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### **CHIP OUTLINE AND PIN ASSIGNMENT**



### Additional Notes:

- 1) Ground Plane must be soldered to PCB RF ground
- 2) All dimensions are in inches
- 3) Refer to Excelics application notes on QFNs for further guidelines
- 4) Pin Assignment:

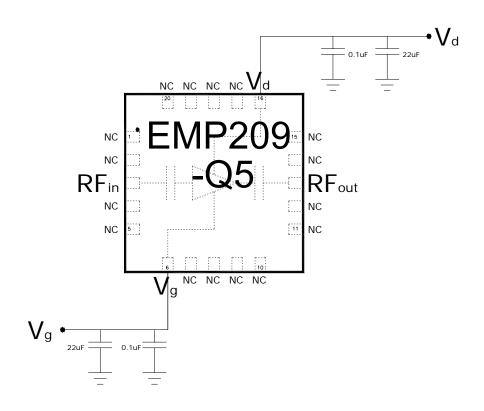


Pin	Assignment
1, 2, 4, 5	NC
3	RF <sub>in</sub>
6	$V_{g}$
7, 8, 9, 10, 11, 12, 14, 15	NC
13	RF <sub>out</sub>
16	$V_d$
17, 18, 19, 20	NC

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## **Recommended Circuit Schematic:**



#### Notes:

- 1) External bypass capacitors should be placed as close to the package as possible.
- 2) Dual biasing sequence required:
  - a. Turn-on Sequence: Apply  $V_g = -2.5V$ , followed by  $V_d = 7V$ , lastly increase  $V_g$  until required  $I_{dq}$
  - b. Turn-off Sequence: Turn off  $V_d$ , followed by  $V_g$
- 3) Demonstration board available upon request.

